

RICH Status Report

TAC, May 1–3, 1997

Hideki Hamagaki

CNS, Tokyo

Who are working for RICH

24 participants:

Faculty/Staff (7), PostDocs (2), Engineers (6), Students (3), Support (6)

8 institutions:

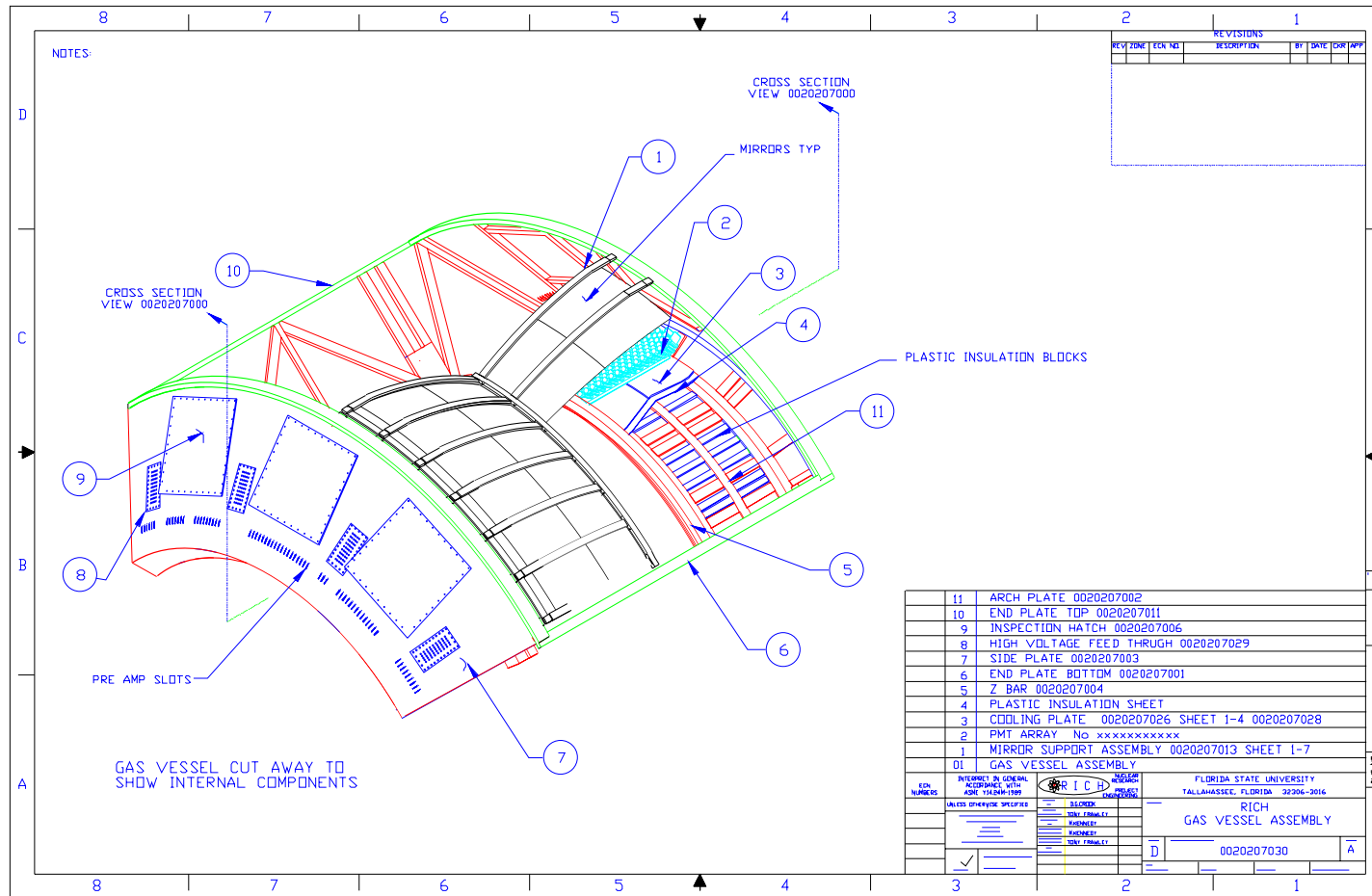
BNL, CNS–Tokyo, FSU, KEK, ORNL, SUNY, U.Tokyo, Waseda

Responsibilities

System Manager (DC Member)
Mechanical Coordinating Physicist
Electronics Coordinating Physicist
Chief Mechanical Engineer
Chief Electronics Engineer
Production Factory Manager at FSU
Production Factory Manager at SUNY
Simulation Computing Coordinator
Off–line Computing Coordinator
On–line Computing Coordinator
Testing Coordinator
Installation Coordinator
Monitoring Coordinator
Calibration Coordinator

H. Hamagaki (CNS–Tokyo)
A. Frawley (FSU)
H. Hamagaki (CNS–Tokyo)
S. Wang (FSU)
A.L. Wintenberg (ORNL)
A. Frawley (FSU)
T.K. Hemmick (SUNY SB)
K. Shigaki (BNL)
Y. Akiba (KEK)
Y. Akiba (KEK)
T.K. Hemmick (SUNY SB)
K. Shigaki (BNL)
K. Shigaki (BNL)
S. Salomone (SUNY SB)

RICH Major Achievements in Last Year



Mechanical:

Final Design Review on April 23, 1997

Supermodule & mirror arrangement optimized

to minimize background from DC frames

PMT

purchased 3500 (out of 5120)

3000 tested at INS and shipped to BNL to SUNY

PMT information in database (by S. Salomone; SUNY)

Supermodule

Design → review → prototype → parts fab.

→ assembled a few tens

assembled supermodules → test → long-term burn-in

Vessel

Final design (construction drawings) → parts order

→ assembly

Mirror

Segments:

Design & prototype (reported in previous TAC)

Mass production starts RSN

Mirror support:

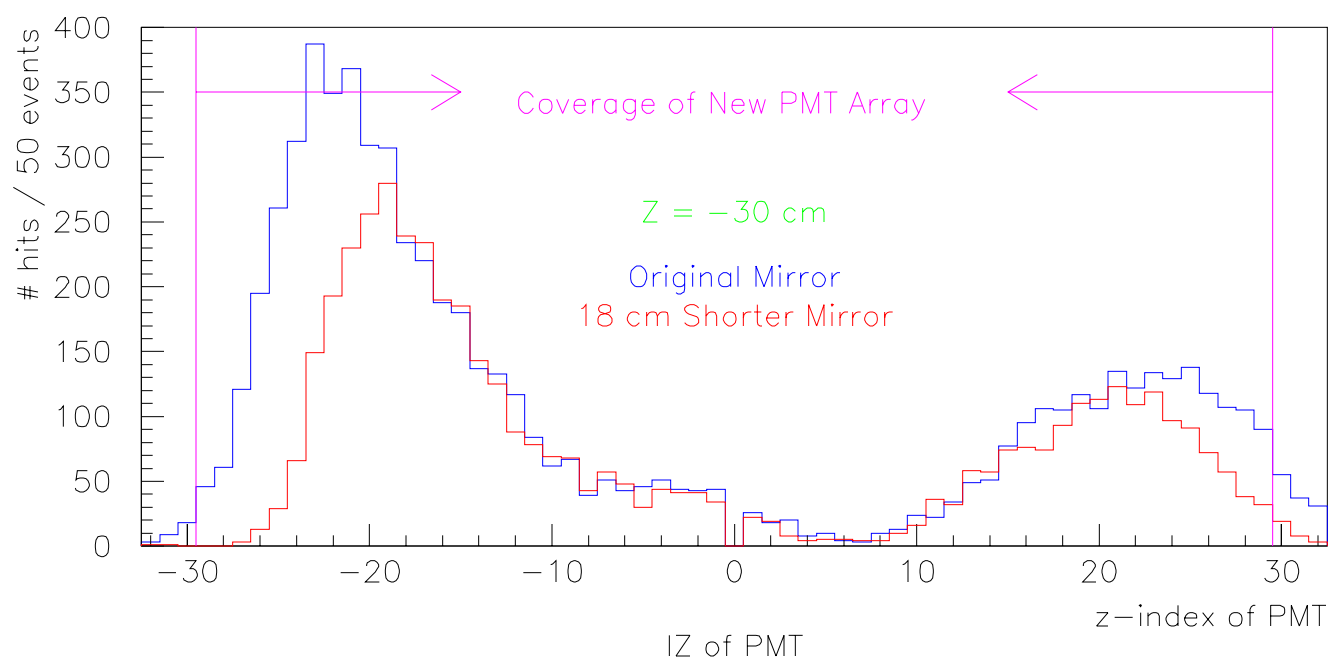
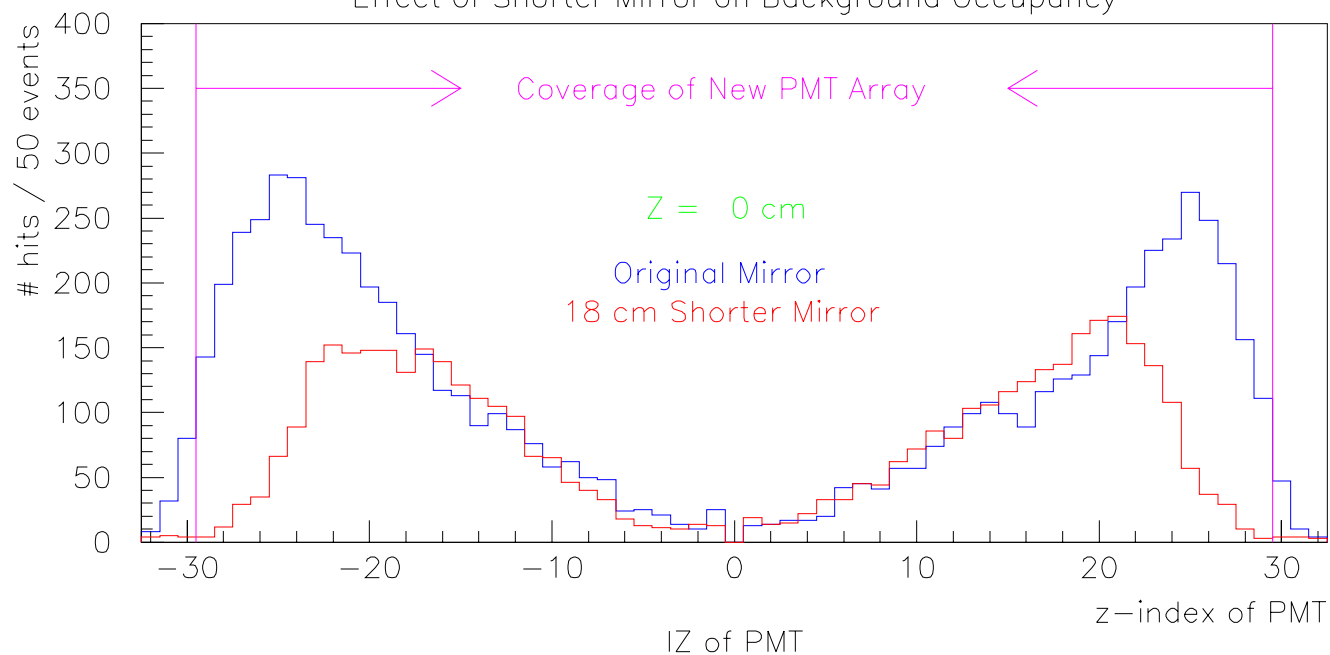
Design in the final stage → production

RICH assembly at Bldg. 832

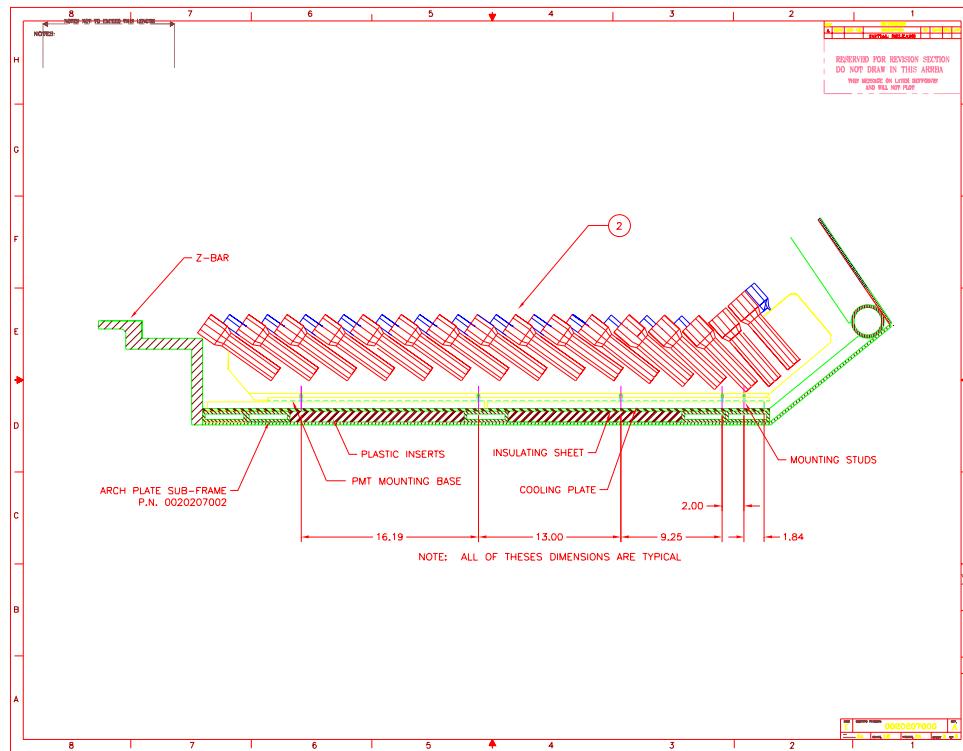
tent design

assembly procedure

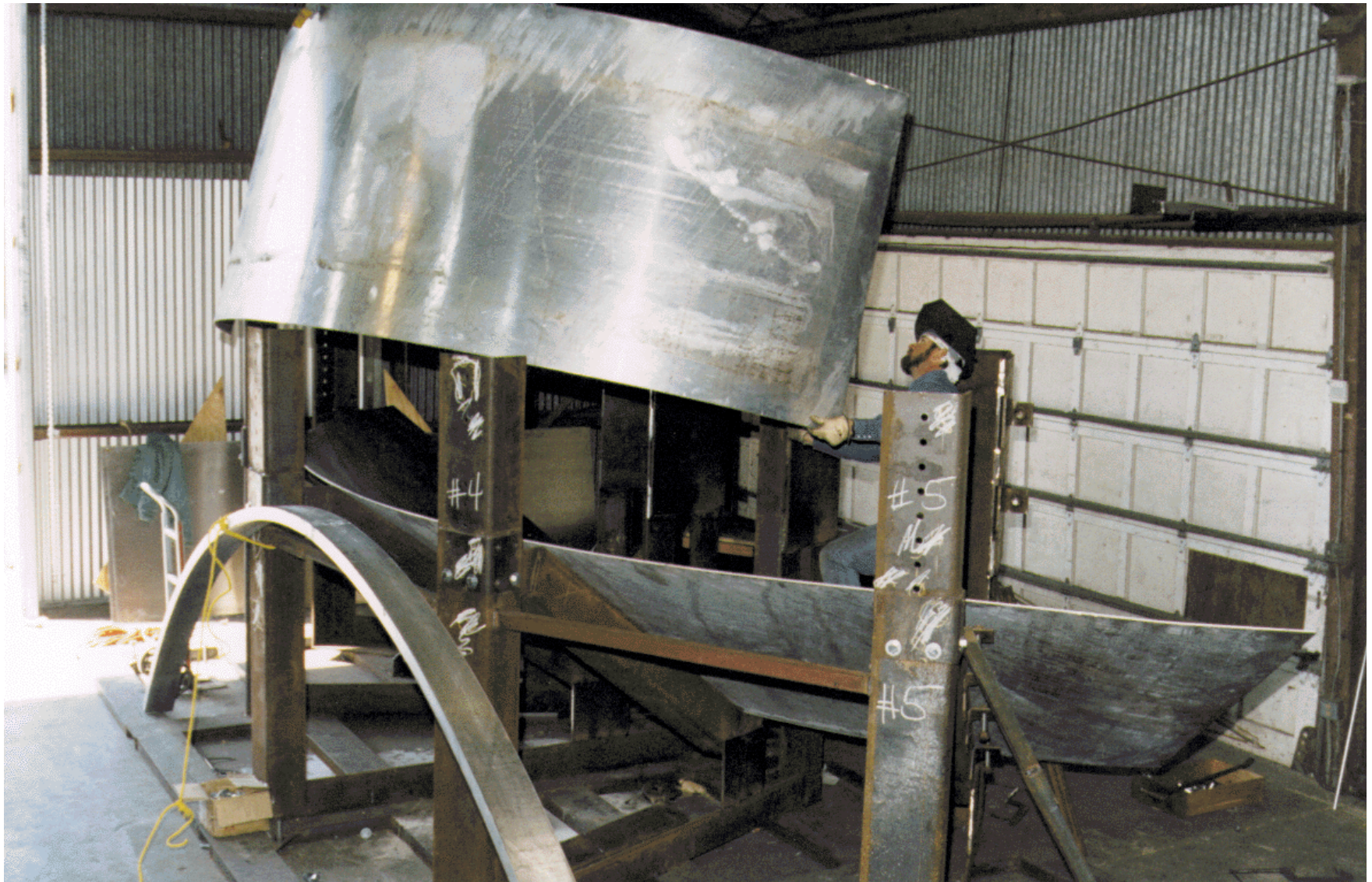
Effect of Shorter Mirror on Background Occupancy



Supermodule Assembly at SUNY



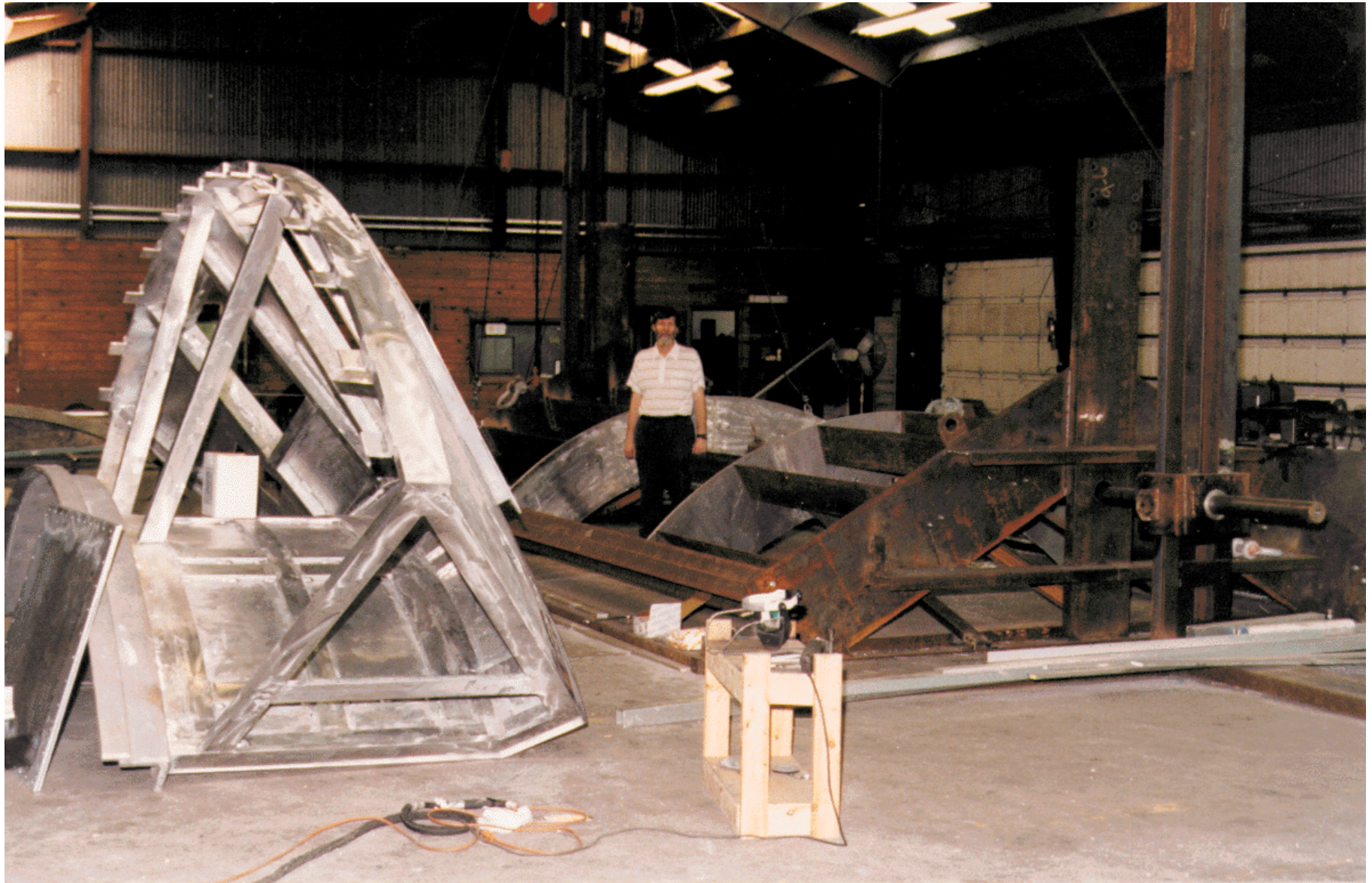
Vessel Fabrication at FSU



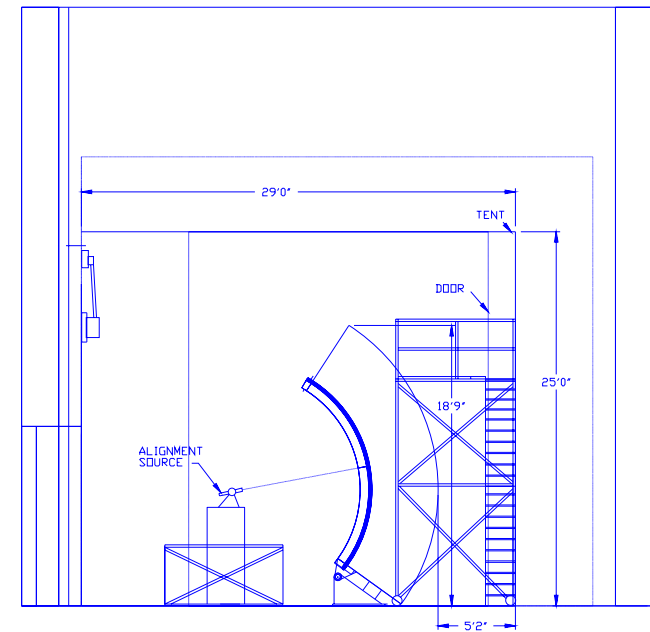
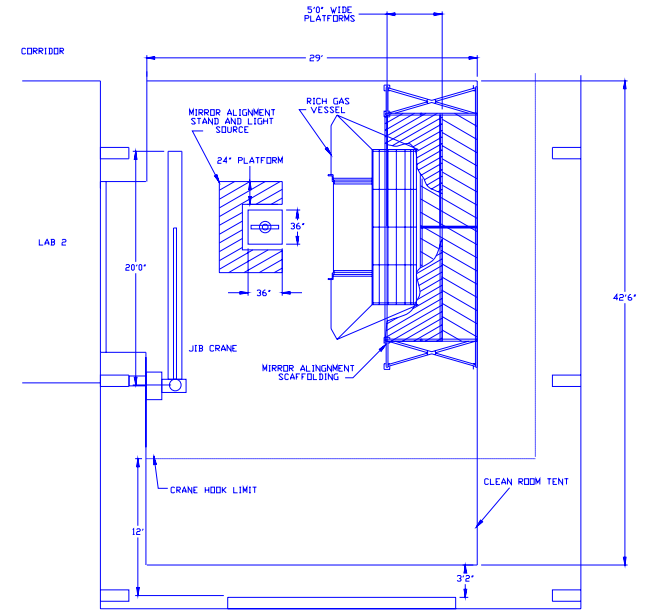
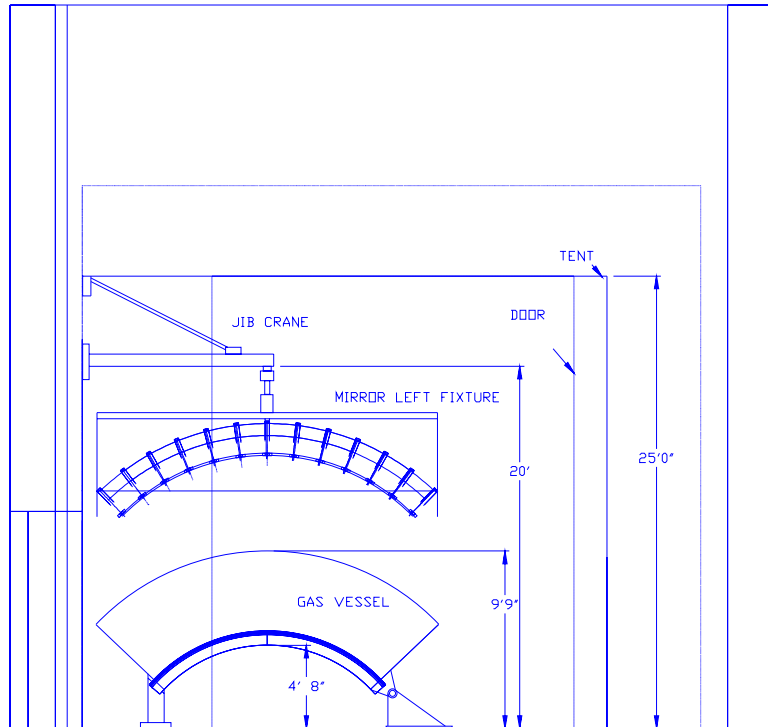
Vessel Fabrication at FSU



Vessel Fabrication at FSU



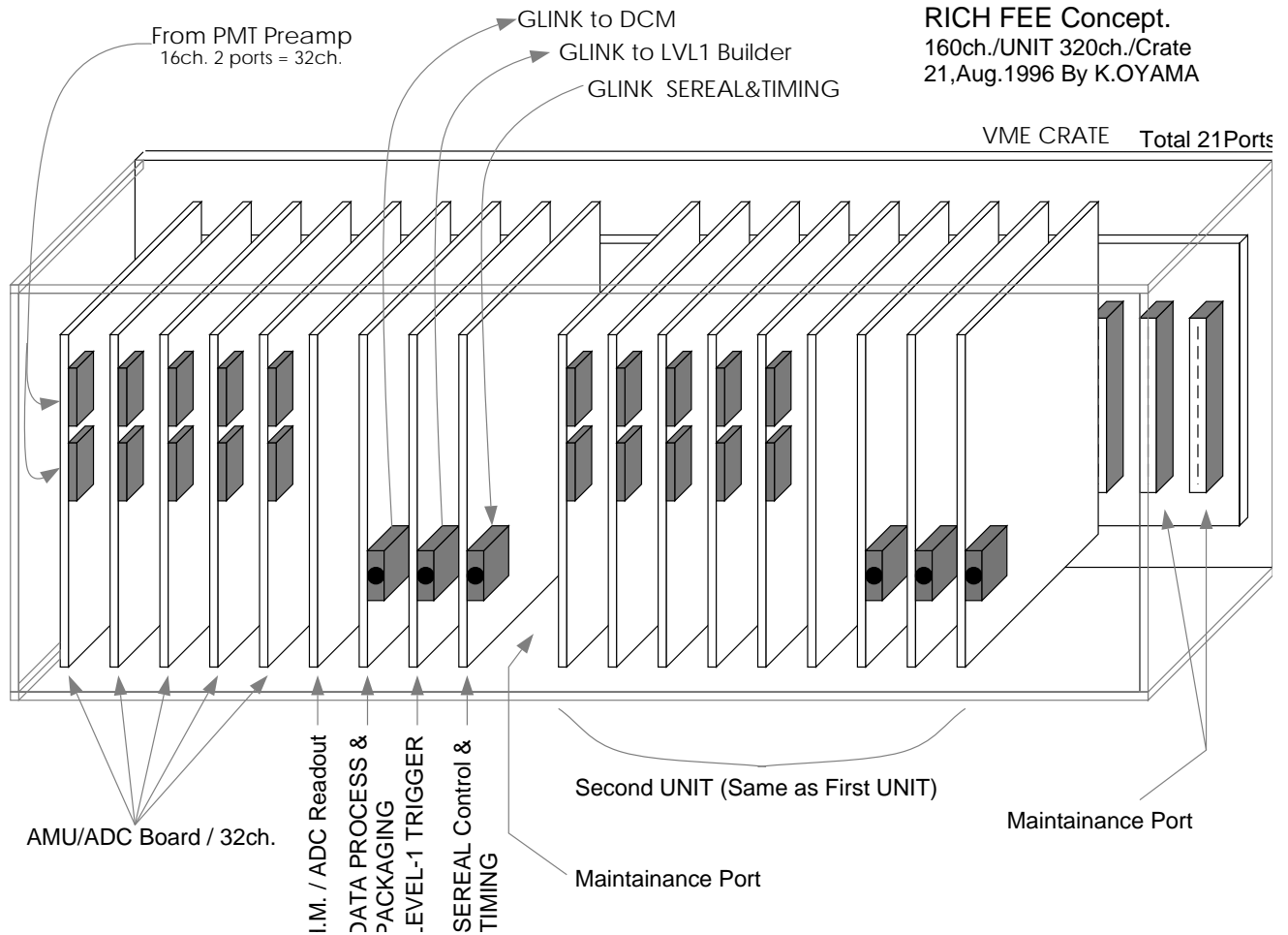
RICH Assembly at Bldg. 832



FEE

FEE specifications fixed

Schematics of RICH FEE made and being improved



FEE Integrator Chip (8CH, analog + TAC)

prototype (1) designed , made and being tested

Schedule/Milestones This Year

Vessels

Complete vessel-1 fabrication	June 1997
Vessel-2	Oct. 1997

Mirrors

Complete 48 mirror segments (for arm-1)	Sep. 1997
Complete mirror support structure	July 1997

Supermodules

Place order of 830 PMT's (~800 left)	June 1997
Complete 80 supermodules (for arm-1)	Aug. 1997

RICH Arm-1 Assembly

Start supermodule installation	July 1997
Complete mirror assembly and alignment	Jan. 1998
RICH arm-1 ready for installation	April 1, 1998

RICH FEE

FEM backplane design	June 1997
Trigger sum circuit prototype	June 1997
Integrator chip prototype test	Summer, 1997
Start design of integrator/AMU board	Fall, 1997
Complete pre-amp	Dec. 1997

Key Issues & Concerns

US/Japan budget is very tight in JFY97

Yen-dollar exchange rate

Share of 1 M\$ reduction of total budget

Vessel/mirror needs ~300 K\$ extra (~25% contingency limit)

Compensation with partial deferral of payment for PMT's

= all PMT's will be delivered to us in JFY97

Partial deferral of FEM fabrication

No impact so far for the installation of RICH arms

Gas-handling scheme & final safety review(s)

a series of reviews will be planned

with the first one in the end of May